

L Number	Hits	Search Text	DB	Time stamp
-	306	451/526.ccls.	USPAT;	2002/12/10 13:20
			US-PGPUB;	
			EPO; JPO	
-	8820	(polish polishing planarize planarizing planarization) with	USPAT;	2002/12/10 11:37
		(conduct conductive electrode electrodes)	US-PGPUB;	
			EPO; JPO	2002/12/10 11:38
] -	1530	((polish polishing planarize planarizing planarization) with	USPAT; US-PGPUB;	2002/12/10 11:36
		(conduct conductive electrode electrodes)) with (pad article	EPO; JPO	
	814	body device) (((polish polishing planarize planarizing planarization) with	USPAT:	2002/12/10 11:39
-	014	(((poils)) poils(ing planarize planarizing planarization) with (conduct conductive electrode electrodes)) with (pad article	US-PGPUB:	2002/12/10 11:00
		body device)) with (substrate wafer semiconductor)	EPO: JPO	
_	142		USPAT:	2002/12/10 19:40
	· '-	10 mp.oolo. and pad man (contractive electrical)	US-PGPUB;	
			EPO; JPO	
-	183	polishing near2 pad with (conductive electrode)	USPAT;	2002/12/10 19:41
			US-PGPUB;	
			EPO; JPO	
-	15		USPAT	2002/12/10 19:46
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		"5944580" "5948700" "6007405" "6010538"		
	,_	"6015754").PN.	LICDAT	2002/42/40 40:54
-	15		USPAT	2002/12/10 19:51
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		"5944580" "5948700" "6007405" "6010538"		
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